ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES® international and I	position De IPC, Bannockt an-American co	c laration ourn, Illinois. A opyright conve	All rights reserved u ntions.	nder both	This docume level parts, t	ent is a declaration er	on of the substan	ces within the ma ower level materia	anufacturer li als for which	isted item. Note: in the manufacture	f the item is an a r has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Ty				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				s Materials a	ials and Mfg Information			
upplier Information													
Company name*			Company unique ID			Unique ID Authority				Response Date*			
onsemi										2024-04-25			
Contact Name Title - Contact			t J		Phone - Contact*			Er	Email - Contact*				
Product-Env-Stewards P			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title			Title - Representative			Phone - Representative*			Er	Email - Representative*			
roduct-Env-Stewards	Product Enviro Compliance				NA			P	Product-Env-Stewards@onsemi.com				
Requester Item Number	Requester Item Number Mfr Item					Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	FCP8501	CP850N80Z SF2 800V 850mC		0hm E TO220		2024-04-25 CNC			2030.181	mg	Each		
Ianufacturing Proccess Inform	ation						-						
Terminal Plating / Grid Array	Terminal Plating / Grid Array Material Terminal Base		Alloy J	J-STD-020 MSL Rating		Peak Process Body Temperature Max Te		ature Max Time	e at Peak Ter	nperature Numb	per of Reflow Cy	cles	
Matte Tin (Sn) - annealed C		CU Alloy NA			0 C 30		30		seconds 3				
omments													
or more information regarding materi	al composition	please refer to	o page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless	otherwise noted).							
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.81	mg	Supplier	Silicon (Si)	7440-21-3		2.81	mg
Die Attach Solder	1.111	mg	Supplier	Silver (Ag)	7440-22-4		0.0278	mg
			А	Lead (Pb)	7439-92-1	7a	1.0277	mg
			Supplier	Tin (Sn)	7440-31-5		0.0555	mg
Lead Frame	1492.12	mg	В	Nickel (Ni)	7440-02-0		0.173	mg
			Supplier	Iron (Fe)	7439-89-6		1.5	mg
			Supplier	Copper (Cu)	7440-50-8		1489.9982	mg
			Supplier	Phosphorus (P)	7723-14-0		0.4489	mg
Mold Compound-Black	518.4	mg		Metal Hydroxide	proprietary data		18.144	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		41.472	mg
			Supplier	Carbon Black (C)	1333-86-4		2.592	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		414.72	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		41.472	mg
Plating	13.3	mg	Supplier	Tin (Sn)	7440-31-5		13.3	mg
Wire Bond - Al	2.44	mg	Supplier	Aluminum (Al)	7429-90-5		2.44	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signa range of distribution unless otherwise noted).